

FJ6K0101

Silicon P-channel MOS FET

For load switch circuits

■ Overview

FJ6K0101 is the low on-resistance P-channel MOS FET designed for load switch circuits.

■ Features

- Low drain-source ON resistance: $R_{DS(on)}$ typ. = 36 m Ω ($V_{GS} = -1.8$ V)
- Low drive voltage: 1.8 V drive
- Small size surface mounting package: WSMINI6-F1-B
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V_{DSS}	-12	V
Gate-source surrender voltage	V_{GSS}	± 8	V
Drain current	I_D	-4.0	A
Peak drain current	I_{DP}	-20	A
Power dissipation *	P_D	700	mW
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: Mounted on a glass epoxy PC board (25.4 mm \times 25.4 mm \times t0.8 mm)
 Absolute maximum rating without heat sink for P_D is 150 mW

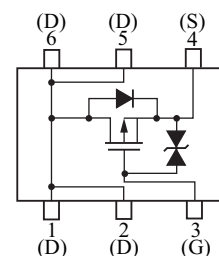
■ Package

- Code
WSMini6-F1-B
- Pin Name

1: Drain	4: Source
2: Drain	5: Drain
3: Gate	6: Drain

■ Marking Symbol: T4

■ Internal Connection

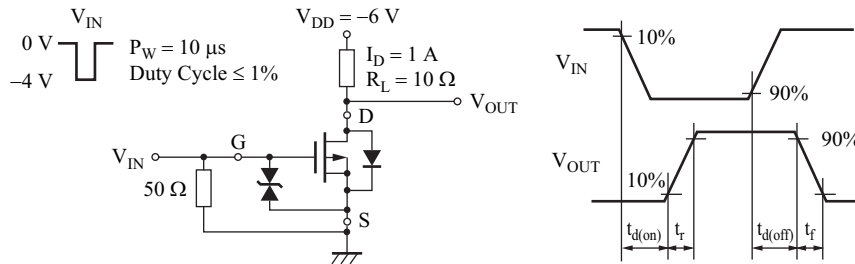


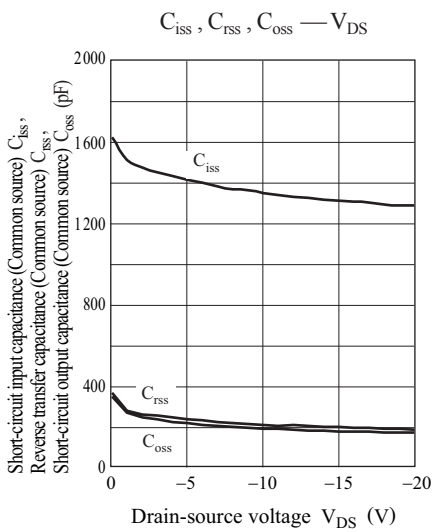
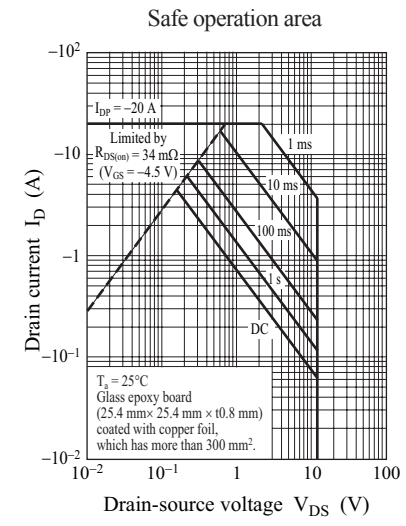
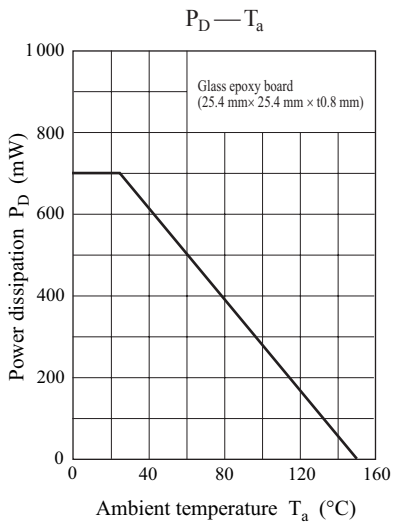
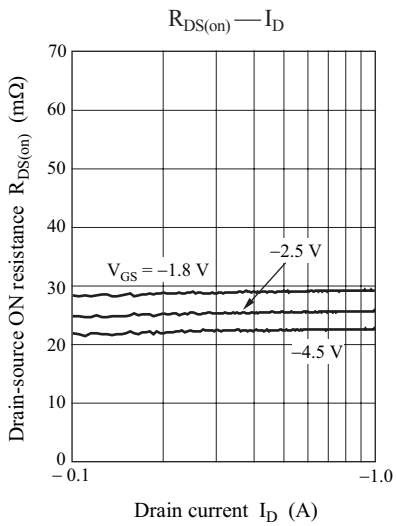
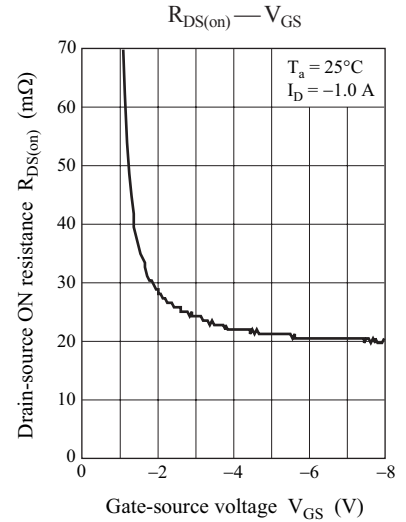
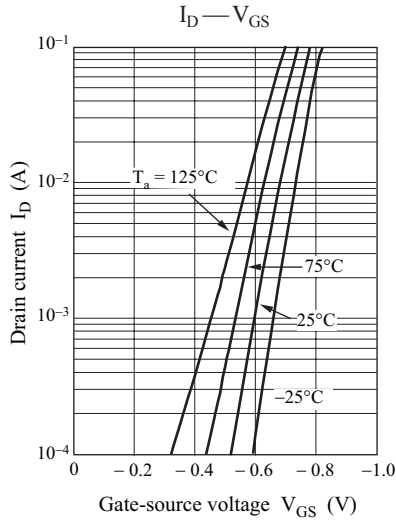
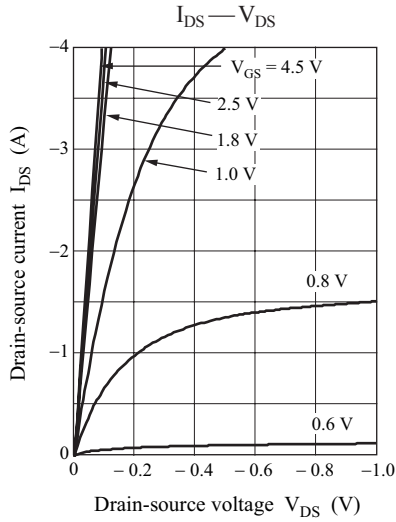
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source surrender voltage	V_{DSS}	$I_D = -1.0 \text{ mA}, V_{GS} = 0$	-12			V
Drain-source cutoff current	I_{DSS}	$V_{DS} = -10 \text{ V}, V_{GS} = 0$			-1.0	μA
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$			± 10	μA
Gate threshold voltage	V_{TH}	$I_D = -1.0 \text{ mA}, V_{DS} = -6.0 \text{ V}$	-0.3	-0.65	-1.0	V
Drain-source ON resistance	$R_{DS(on)}$	$I_D = -1.0 \text{ A}, V_{GS} = -4.5 \text{ V}$		26	34	m Ω
		$I_D = -0.5 \text{ A}, V_{GS} = -2.5 \text{ V}$		30	41	
		$I_D = -0.5 \text{ A}, V_{GS} = -1.8 \text{ V}$		36	54	
Forward transfer admittance	$ Y_{fs} $	$I_D = -1.0 \text{ A}, V_{DS} = -10 \text{ V}$	4.0			S
Short-circuit input capacitance (Common source)	C_{iss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		1 400		pF
Short-circuit output capacitance (Common source)	C_{oss}			190		pF
Reverse transfer capacitance (Common source)	C_{rss}			210		pF
Turn-on delay time *	$t_{d(on)}$	$V_{DD} = -6.0 \text{ V}, V_{GS} = 0 \text{ V to } -4 \text{ V}, I_D = -1.0 \text{ A}$		9		ns
Rise time *	t_r			40		ns
Turn-off delay time *	$t_{d(off)}$	$V_{DD} = -6.0 \text{ V}, V_{GS} = -4 \text{ V to } 0 \text{ V}, I_D = -1.0 \text{ A}$		250		ns
Fall time *	t_f			150		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

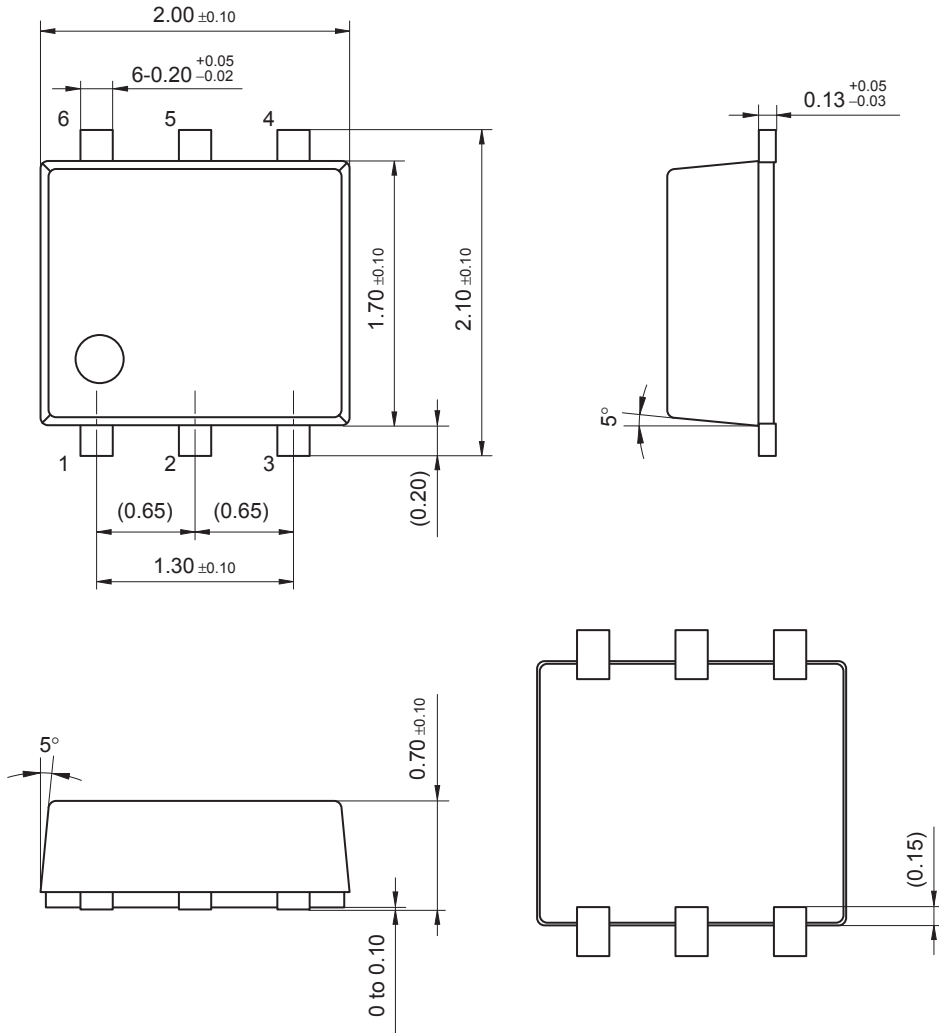
2. *: t_{on} , t_{off} measurement circuit





WSMini6-F1-B

Unit: mm



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